

SOT1969-1

HX2QFN20, thermal enhanced super thin quad flat package;
no leads; 20 terminals, 0.4 mm pitch, 3.0 mm x 3.0 mm x 0.32
mm body

23 May 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HX2QFN20
JEDEC package outline code	MO-288
Mounting method type	S (surface mount)
Issue date	16-05-2019
Manufacturer package code	98ASA01228D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.9	3	3.1	mm
seated height	0.3	0.32	0.33	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	20	-	



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2 Package outline

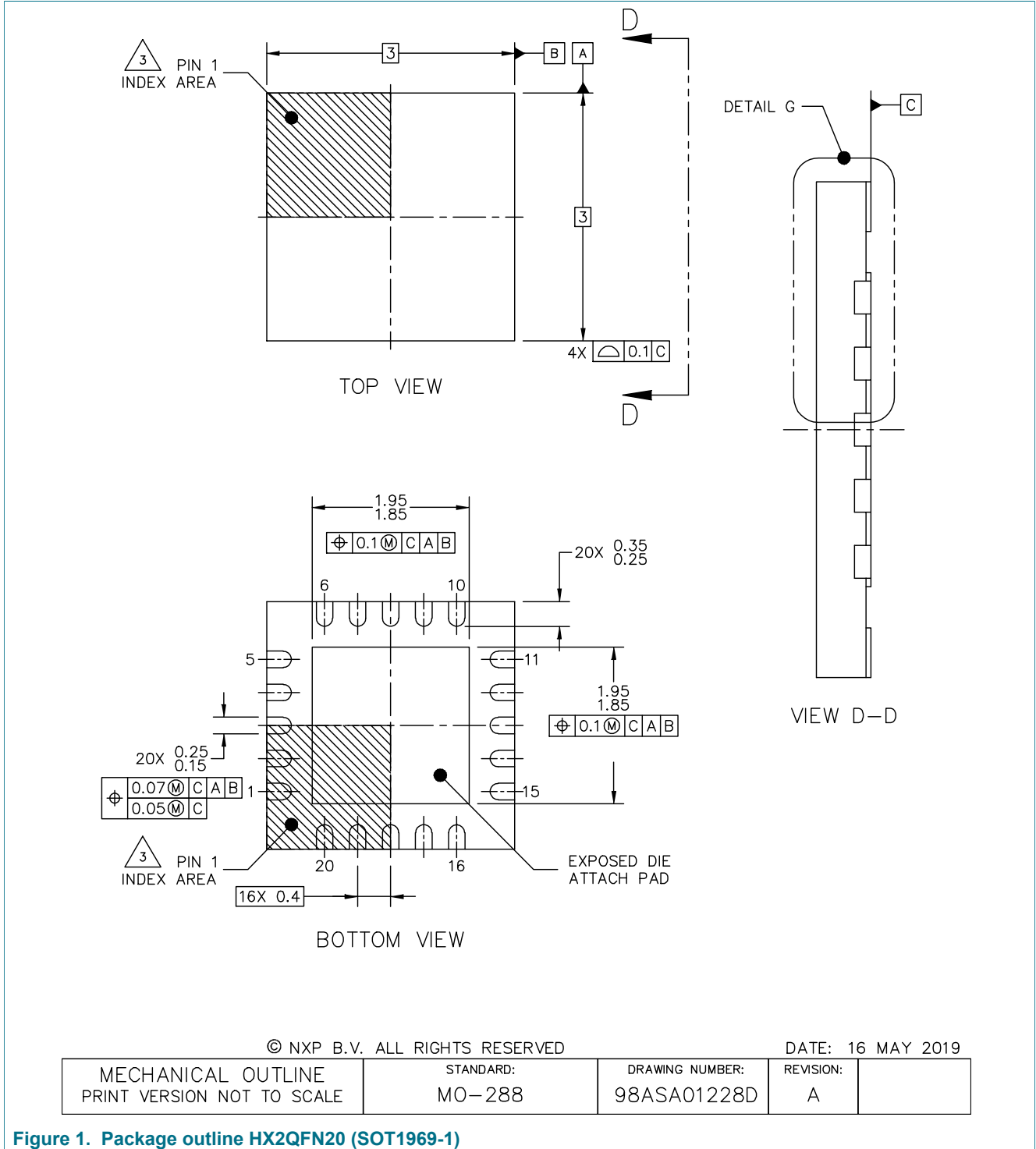


Figure 1. Package outline HX2QFN20 (SOT1969-1)

HX2QFN20, thermal enhanced super thin quad flat package; no leads; 20 terminals, 0.4 mm pitch, 3.0 mm x 3.0 mm x 0.32 mm body

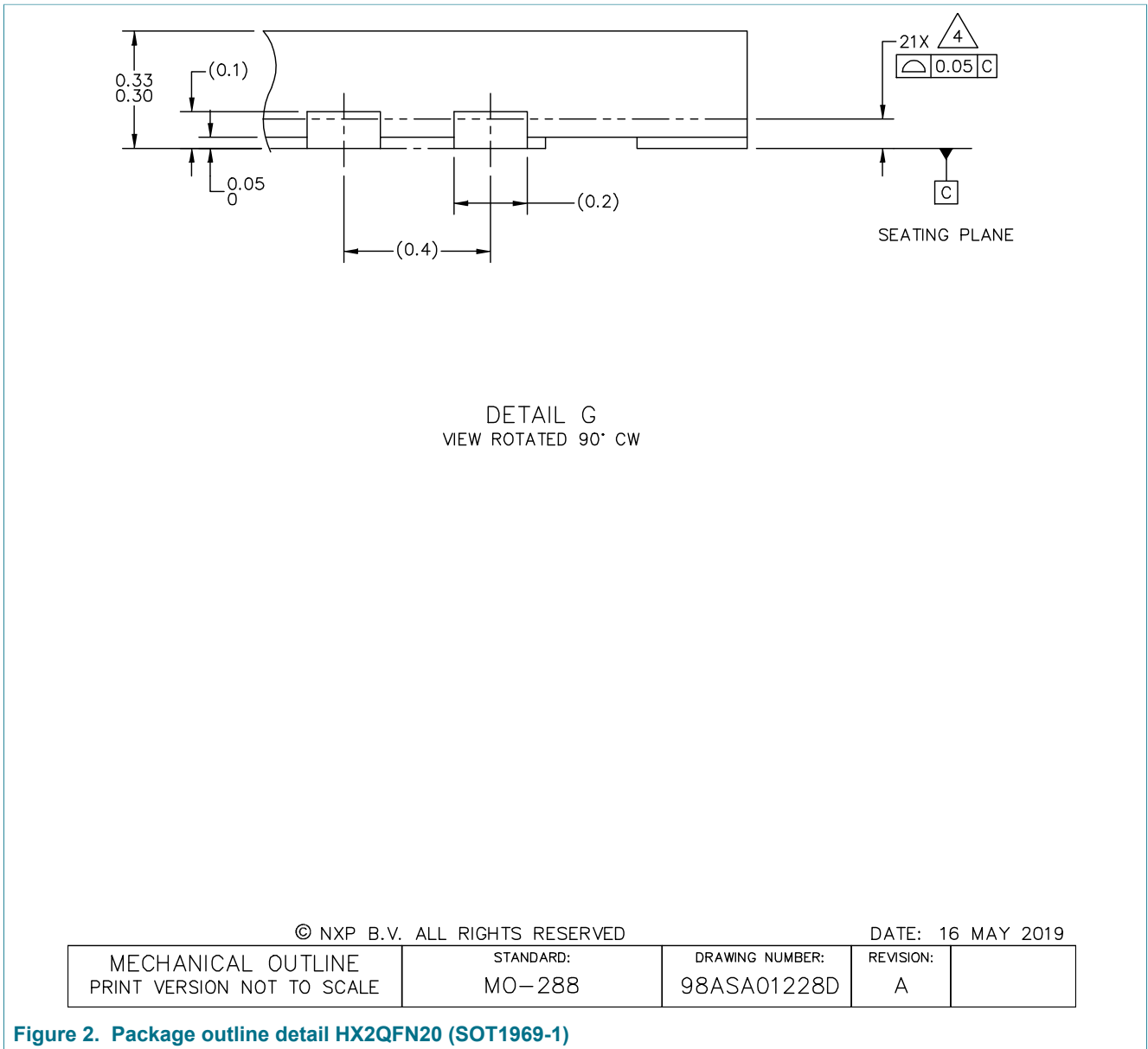


Figure 2. Package outline detail HX2QFN20 (SOT1969-1)

HX2QFN20, thermal enhanced super thin quad flat package; no leads; 20 terminals, 0.4 mm pitch, 3.0 mm x 3.0 mm x 0.32 mm body

3 Soldering

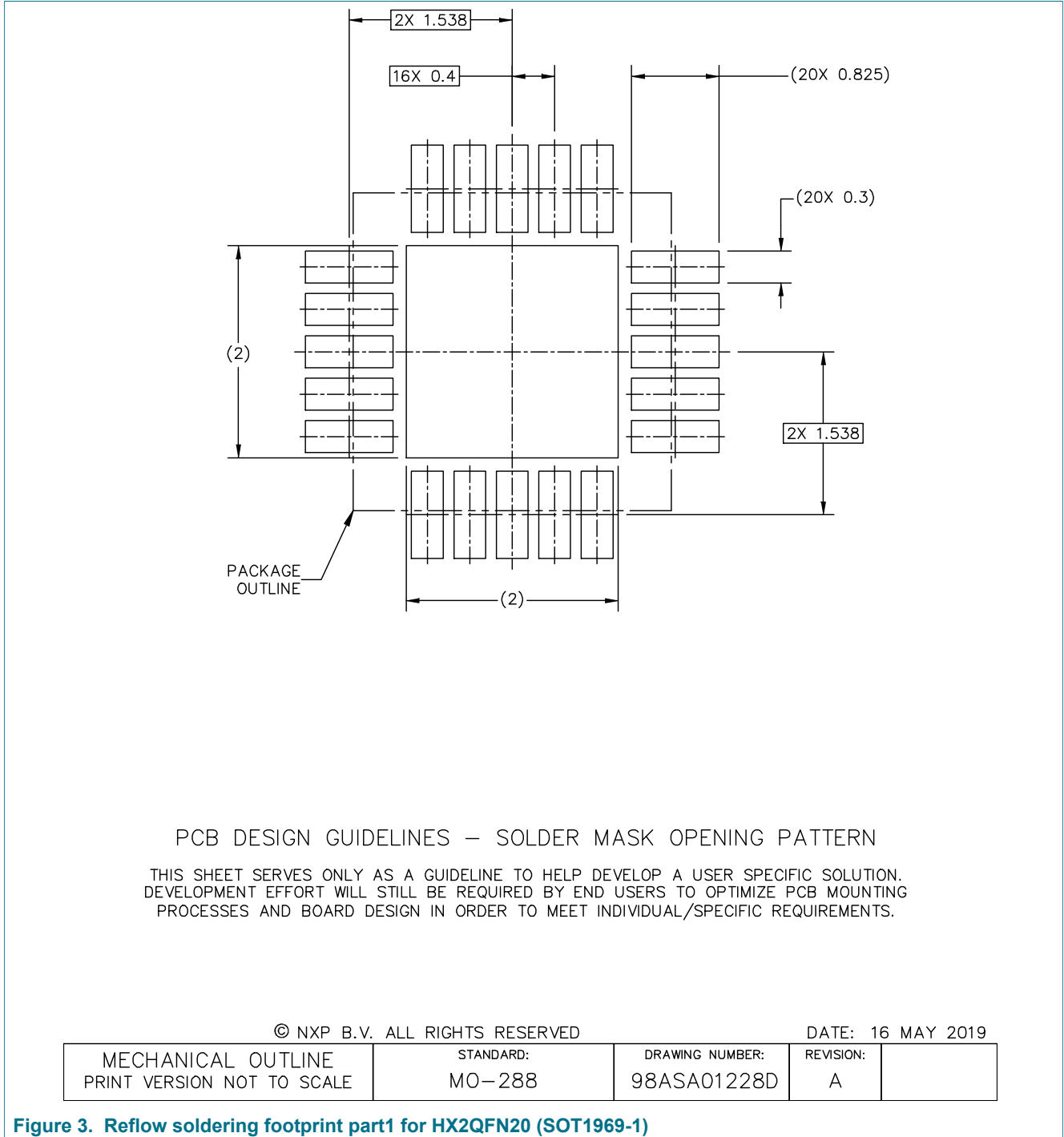
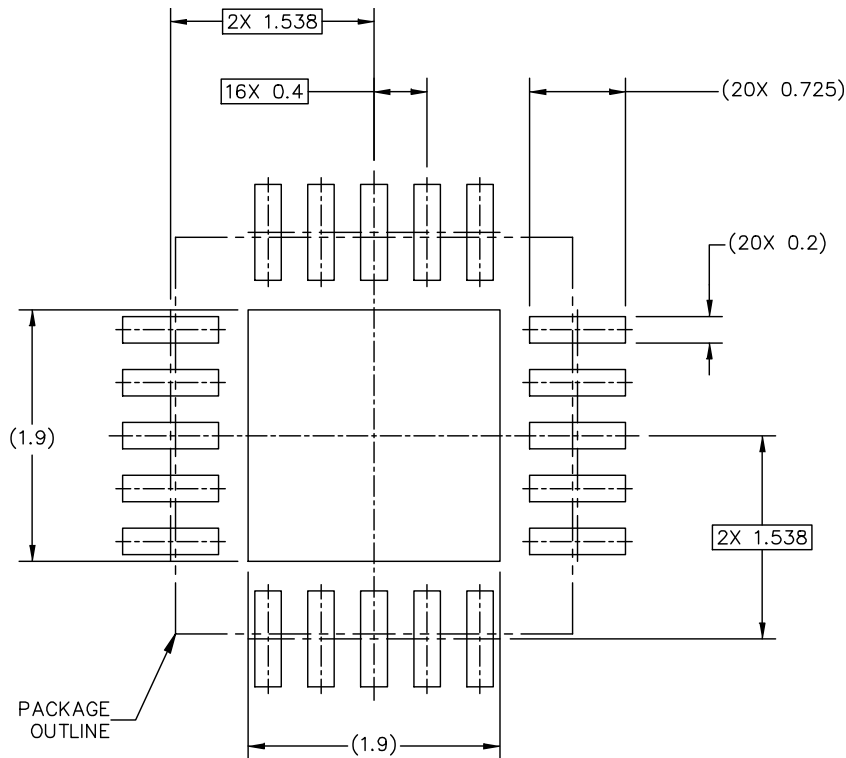


Figure 3. Reflow soldering footprint part1 for HX2QFN20 (SOT1969-1)

HX2QFN20, thermal enhanced super thin quad flat package; no leads; 20 terminals, 0.4 mm pitch, 3.0 mm x 3.0 mm body



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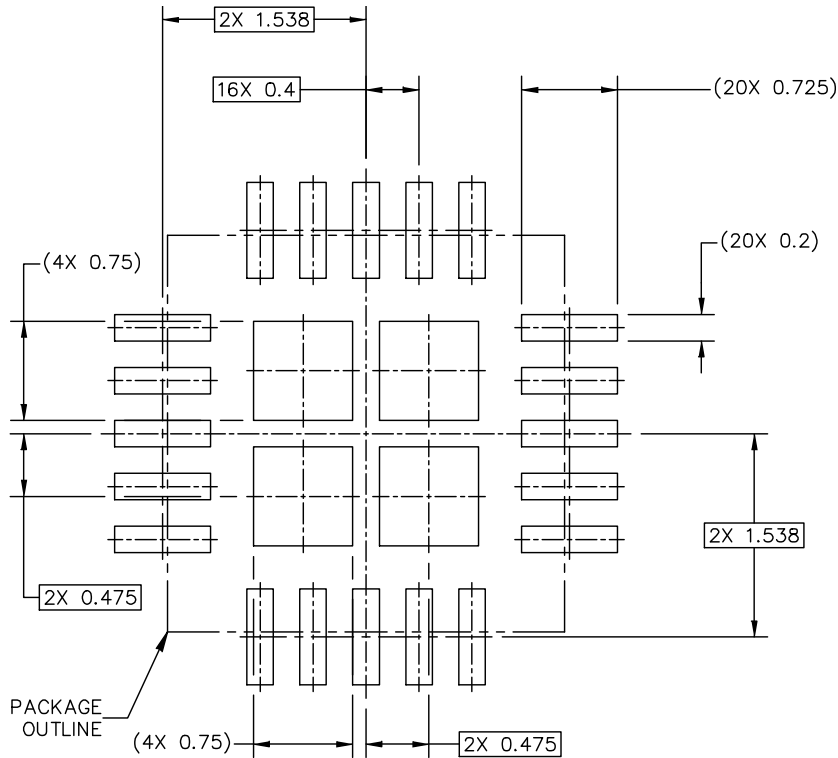
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Figure 4. Reflow soldering footprint part2 for HX2QFN20 (SOT1969-1)

HX2QFN20, thermal enhanced super thin quad flat package; no leads; 20 terminals, 0.4 mm pitch, 3.0 mm x 3.0 mm x 0.32 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HX2QFN20 (SOT1969-1)

HX2QFN20, thermal enhanced super thin quad flat package; no leads; 20 terminals, 0.4 mm pitch, 3.0 mm x 3.0 mm x 0.32 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND EXPOSED PAD ON BOTTOM SIDE.
5. MIN. METAL GAP SHOULD BE 0.15 MM.

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Figure 6. Package outline note HX2QFN20 (SOT1969-1)

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